

U/I P/E
JAN 29 2001
PATENT & TRADEMARK OFFICE

Atty Docket No.

KLA1P016G

Application No.:

09/648,381

Information Disclosure
Statement By Applicant

(Use Several Sheets if Necessary)

Applicant:

Satya, et al

Filing Date

August 25, 2000

Group

2881

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<i>AS</i>	A1	5,959,459	9-28-99	Satya et al.	324	751	12-10-96
<i>AS</i>	A2	6,021,214	2-1-00	Evans et al.	382	141	9-7-95
<i>AS</i>	A3	5,537,669	7-16-96	Evans et al.	382	141	9-30-93
<i>AS</i>	A4	4,644,172	2-17-87	Sandland et al.	250	548	2-22-84
<i>AS</i>	A5	5,502,306	3-26-96	Meisburger et al.	250	310	3-17-94
<i>AS</i>	A6	5,578,821	11-26-96	Meisburger et al.	250	310	1-11-95
<i>AS</i>	A7	5,665,968	9-9-97	Meisburger et al.	250	310	2-26-96
<i>AS</i>	A8	5,717,204	2-10-98	Meisburger et al.	250	310	2-26-96

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
<i>AS</i>	B1	0 853 243 A2	7-15-98	EPO	G01R	31/307	X	
<i>AS</i>	B2	0 892 275 A2	1-20-99	EPO	G01R	31/305	X	
<i>AS</i>	B3	WO 99/22310	5-6-99	WIPO	G06F	17/00	X	
<i>AS</i>	B4	WO 99/22311	5-6-99	WIPO	G06F	17/00	X	

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
<i>AS</i>	C1	Tugbawa, et al, " Pattern And Process Dependencies In Copper Damascene Chemical Mechanical Polishing Processes," June 1998, VLSI Multilevel Interconnect conference (VMIC)
<i>AS</i>	C2	Park et al, "Multi-Level Pattern Effects In Copper CMP," Oct 1999, CMP Symposium Electrochemical Society Meeting
<i>AS</i>	C3	
Examiner	<i>Andre Stevens</i>	Date Considered <i>09/14/03</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.